applied MICROswiss

High-definition microstructured Stencil masks: Specifications

- Pattern size > 5µm
- Thickness of stencil masks = 20 - 500µm
- Material: Nickel, Nickel-Phos12, stainless
- Aspect ratio = 5 - 6 (depends on pattern-design)
- EXCLUSIVE: adjustable pattern-tapering up to 15°
- Manufacturing according to adapted LiGA-process
- Multilevel pattern available (e.g. increase part-stiffness)
- Alignment-precision level-to-level ≤ 3 µm
- Maximal patterned area = 200 x 200mm
- Parallelism Frontside-to-backside ≤ 10 µm
- Available PVD-coating
- Compatible photoresists for UV-Lithography:
  - AZ positive resists, MicroChem SU-8